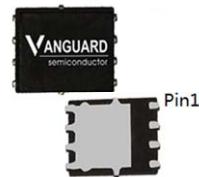


## Features

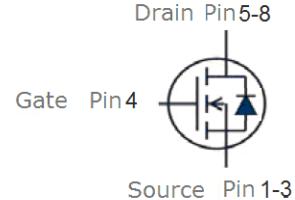
- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5$  V
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

$V_{DS}$	60	V
$R_{DS(on),TYP}@ V_{GS}=10$ V	7.2	mΩ
$R_{DS(on),TYP}@ V_{GS}=4.5$ V	8.8	mΩ
$I_D$	70	A

PDFN5x6



Part ID	Package Type	Marking	Tape and reel information
VS6020AP	PDFN5x6	6020AP	3000pcs/Reel



## Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		60	V
$I_s$	Diode continuous forward current	$T_c=25$ °C	70	A
$I_D$	Continuous drain current@ $V_{GS}=10$ V	$T_c=25$ °C	70	A
		$T_c=100$ °C	44	A
$I_{DM}$	Pulse drain current tested ①	$T_c=25$ °C	200	A
EAS	Avalanche energy, single pulsed ②		56	mJ
IAS	Avalanche Current max	$L=0.1mH$	55	A
$P_d$	Maximum power dissipation	$T_c=25$ °C	69	W
$V_{GS}$	Gate-Source voltage		±20	V
$T_{STG} T_j$	Storage and operating temperature range		-55 to 150	°C

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	40	°C/W

## Typical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>c</sub> =25°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =125°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	2.0	3.0	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance③	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	--	7.2	9.0	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance③	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	--	8.8	12.0	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>c</sub>= 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	--	2270	--	pF
C <sub>oss</sub>	Output Capacitance		--	205	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	195	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	1.2	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V	--	26	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	6.5	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	4.5	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =10A, R <sub>G</sub> =6.8Ω, V <sub>GS</sub> =10V	--	9	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	5	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	28	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	4	--	nS
<b>Source- Drain Diode Characteristics@ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =30A, V <sub>GS</sub> =0V	--	0.84	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>sd</sub> =20A, V <sub>GS</sub> =0V di/dt=500A/μs	--	23	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	58	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>jmax</sub>, starting T<sub>j</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 15A, V<sub>GS</sub> = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle≤ 2%.



## Typical Characteristics

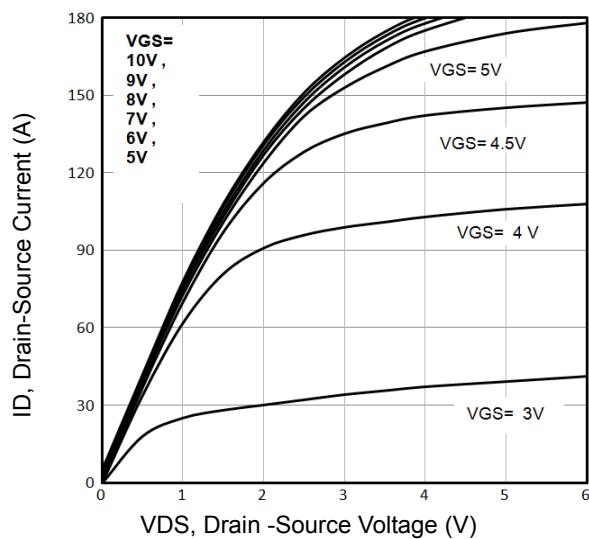


Fig1. Typical Output Characteristics

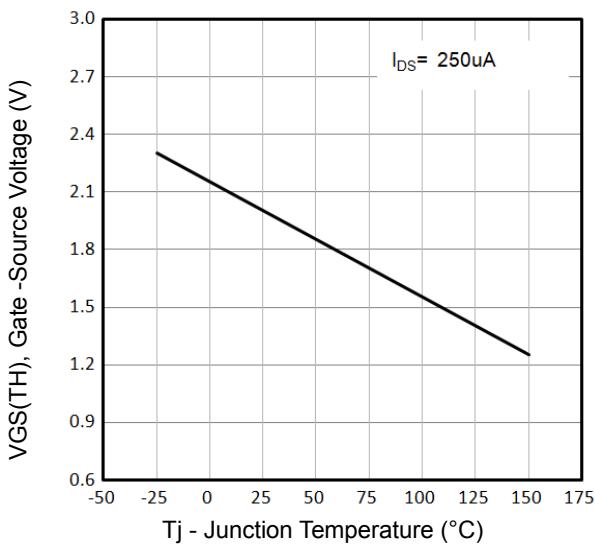


Fig2.  $V_{GS(TH)}$  Gate-Source Voltage Vs.  $T_j$

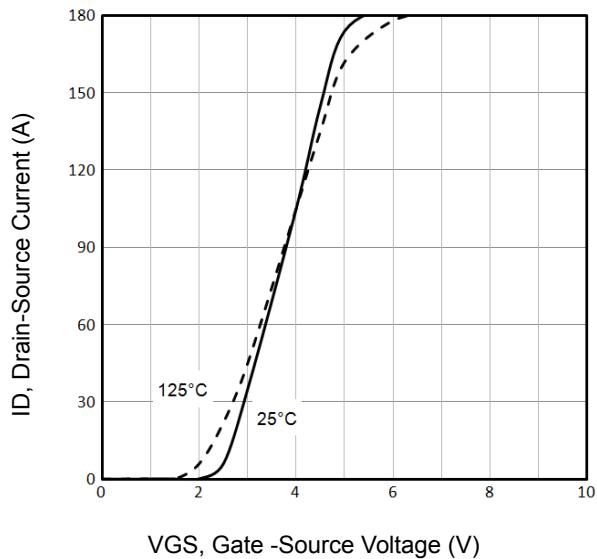


Fig3. Typical Transfer Characteristics

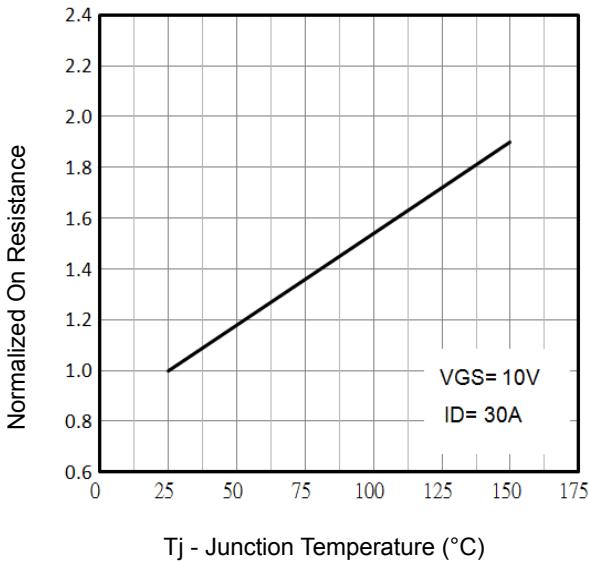


Fig4. Normalized On-Resistance Vs.  $T_j$

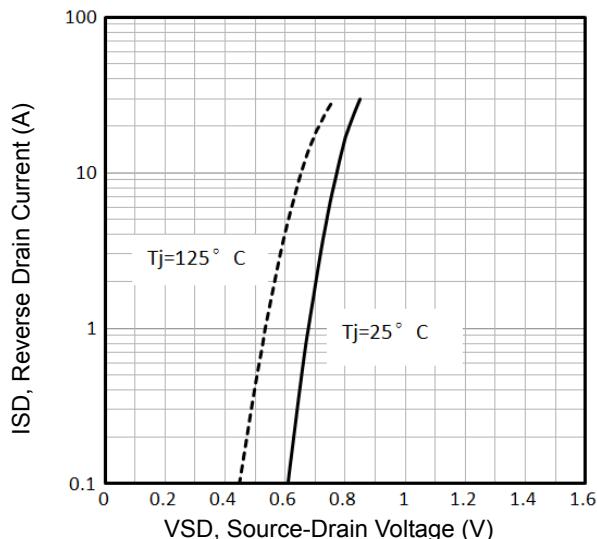


Fig5. Typical Source-Drain Diode Forward Voltage

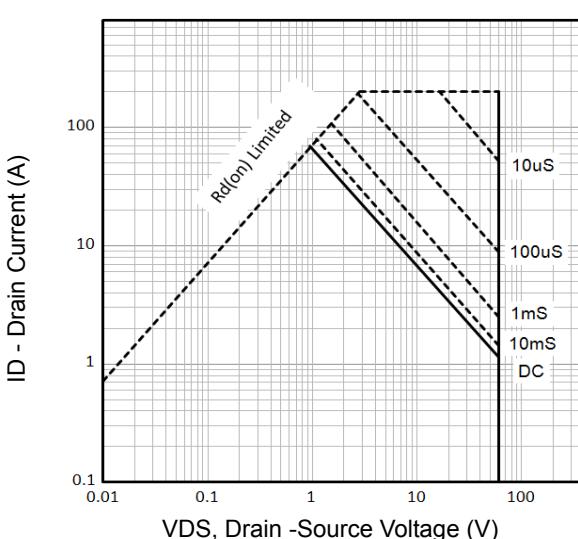
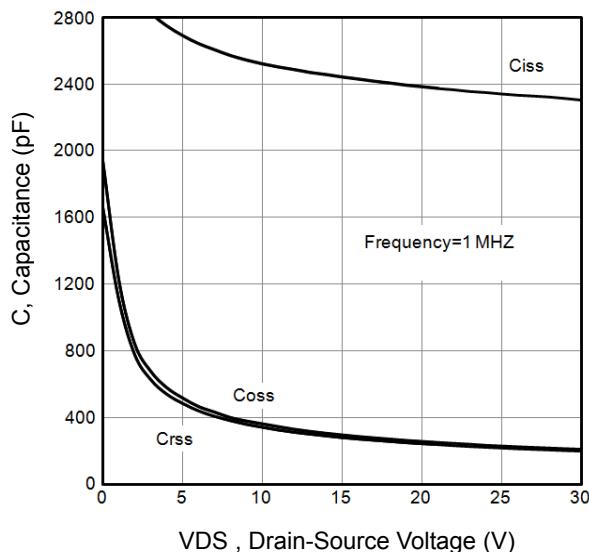


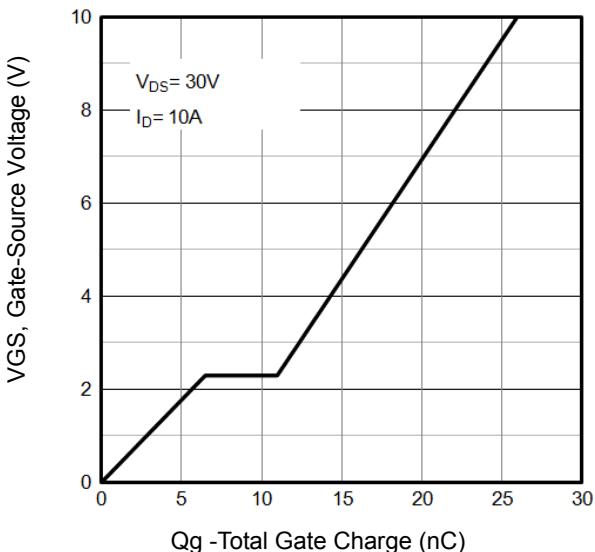
Fig6. Maximum Safe Operating Area



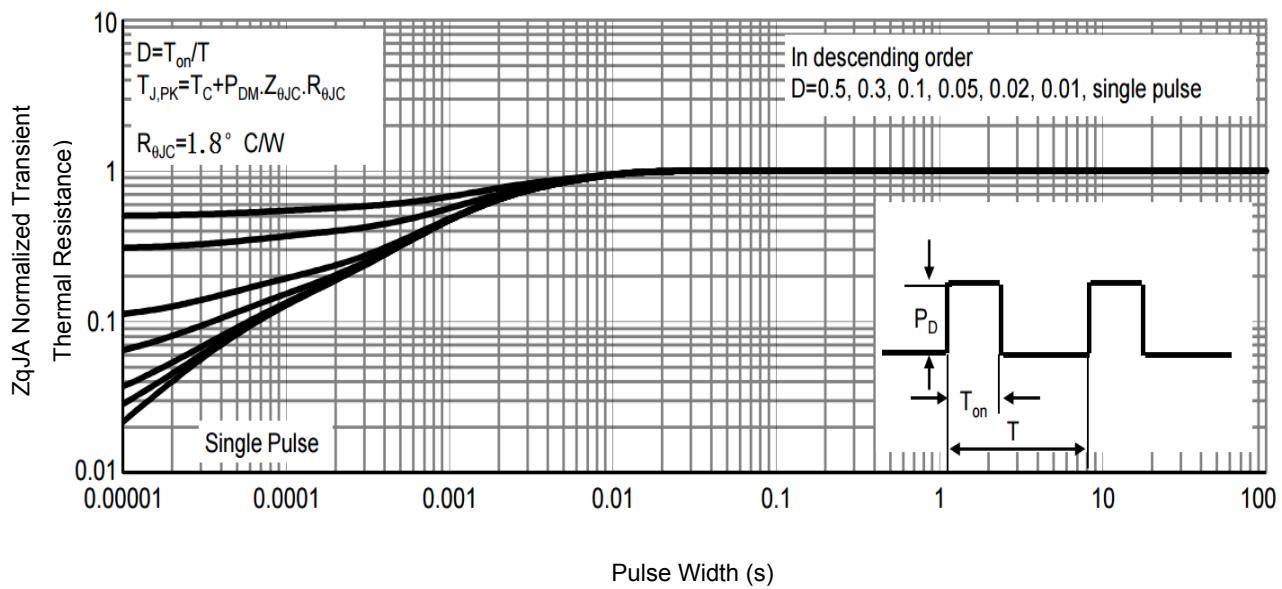
## Typical Characteristics



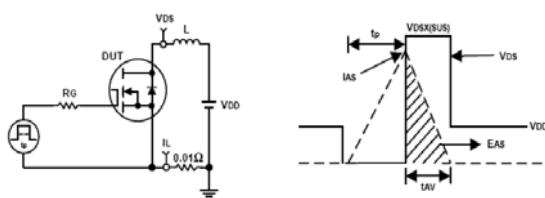
**Fig7.** Typical Capacitance Vs.Drain-Source Voltage



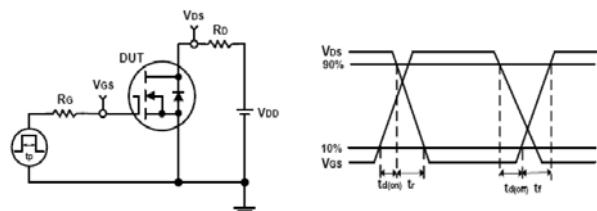
**Fig8.** Typical Gate Charge Vs.Gate-Source Voltage



**Fig9 .**Normalized Maximum Transient Thermal Impedance

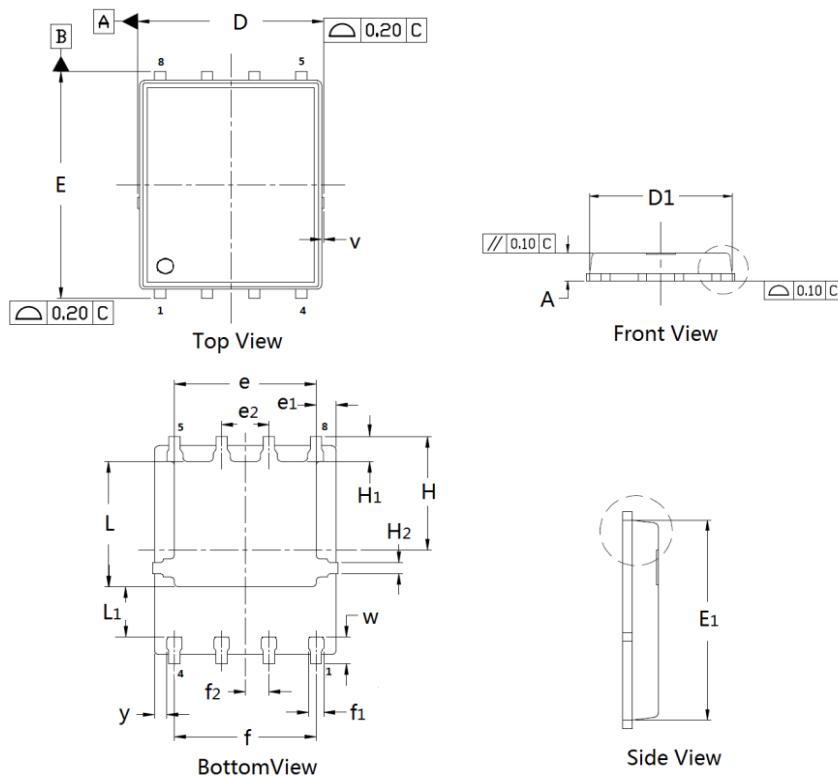


**Fig10.** Unclamped Inductive Test Circuit and waveforms



**Fig11.** Switching Time Test Circuit and waveforms

### PDFN5×6 Package Outline Data



#### DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D <sub>1</sub>	4.80	4.89	5.00	E	6.00	6.11	6.20
E <sub>1</sub>	5.65	5.74	5.85	e	3.72	3.80	3.92
e <sub>1</sub>	--	0.54	--	e <sub>2</sub>	--	1.27	--
f	--	3.82	--	f <sub>1</sub>	0.31	0.37	0.51
f <sub>2</sub>	--	0.64	--	H	--	3.15	--
H <sub>1</sub>	0.59	0.63	0.79	H <sub>2</sub>	0.26	0.28	0.32
L	3.38	3.45	3.58	L <sub>1</sub>	--	1.39	--
v	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--

### Customer Service

#### Sales and Service:

[sales@vgsemi.com](mailto:sales@vgsemi.com)

**Vanguard Semiconductor CO., LTD**

**TEL:** (86-755) -26902410

**FAX:** (86-755) -26907027

**WEB:** [www.vgsemi.com](http://www.vgsemi.com)